VBZ2301

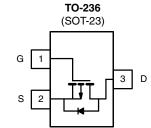
V_{DS} (V)

Configuration

PRODUCT SUMMARY

 $\mathsf{R}_{\text{DS(on)}}\left(\Omega\right)$ at V_{GS} = - 4.5 V

 $R_{DS(on)}(\Omega)$ at $V_{GS} = -2.5$ V



P-Channel 20 V (D-S) MOSFET

- 20

0.060

0.085

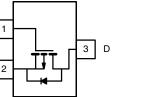
- 4

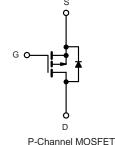
Single

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % $R_{\rm q}$ and UIS Tested
- Compliant to RoHS Directive 2002/95/EC







ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted) PARAMETER SYMBOL LIMIT UNIT Drain-Source Voltage V_{DS} - 20 V V_{GS} Gate-Source Voltage ± 12 T_C = 25 °C - 4 **Continuous Drain Current** I_{D} T_C = 125 °C - 2.5 Continuous Source Current (Diode Conduction)^a ls - 5 А Pulsed Drain Current^b I_{DM} -15 Single Pulse Avalanche Current I_{AS} - 6 L = 0.1 mH E_{AS} Single Pulse Avalanche Energy 4 mJ $T_C = 25 \circ C$ 3 Maximum Power Dissipation^b P_{D} W T_C = 125 °C 1 °C Operating Junction and Storage Temperature Range - 55 to + 175 T_J, T_{stq}

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	166	°C/W
Junction-to-Foot (Drain)	nction-to-Foot (Drain)		50	C/W

Notes

a. Package limited.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. When mounted on 1" square PCB (FR-4 material).

d. Parametric verification ongoing.







SPECIFICATIONS (T _C = 25 °C	, unless otherv	vise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = -250 \ \mu A$		- 20	-	-	v	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = - 250 μA	- 0.45	-	- 1.5	v	
Gate-Source Leakage	I _{GSS}	V _{DS} =	= 0 V, V _{GS} = ± 8 V	-	-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = - 20 V	I	-	- 1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V_{DS} = - 20 V, T_J = 125 °C	-	-	- 50	μA	
		$V_{GS} = 0 V$	V_{DS} = - 20 V, T_J = 175 °C	-	-	- 150		
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = -4.5 V$	$V_{DS} \ge 5 V$	- 8	-	-	Α	
Drain-Source On-State Resistance ^a	P	$V_{GS} = -4.5 V$	I _D = - 2.8 A	-	0.060	-	Ω	
	R _{DS(on)}	$V_{GS} = -2.5 V$	I _D = - 2 A	-	0.085	-		
Forward Transconductance ^a	g fs	V _{DS} = - 1.6 V, I _D = - 2.8 A		-	7	-	S	
Dynamic ^b	·	-						
Input Capacitance	C _{iss}		V _{DS} = - 10 V, f = 1 MHz	-	340	425	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	80	100		
Reverse Transfer Capacitance	C _{rss}			-	55	70		
Total Gate Charge ^c	Qg			-	5	8		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = - 4.5 V	V_{DS} = - 10 V, I_{D} = - 2.8 A	-	0.7	-	nC	
Gate-Drain Charge ^c	Q _{gd}			-	1.3	-		
Gate Resistance	Rg	f = 1 MHz		5.5	10	14.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	15	22		
Rise Time ^c	t _r	$V_{DD} = -10 \text{ V}, \text{ R}_{L} = 10 \Omega$ $\text{I}_{D} \cong -1 \text{ A}, \text{ V}_{\text{GEN}} = -4.5 \text{ V}, \text{ R}_{g} = 1 \Omega$		-	14	21	- ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	30	45		
Fall Time ^c	t _f			-	9	15		
Source-Drain Diode Ratings and Char	acteristics ^b				·	·	•	
Pulsed Current ^a	I _{SM}			-	-	- 3	А	
Forward Voltage	V _{SD}	I _F =	- 1.6 A, V _{GS} = 0	-	- 0.8	- 1.2	V	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

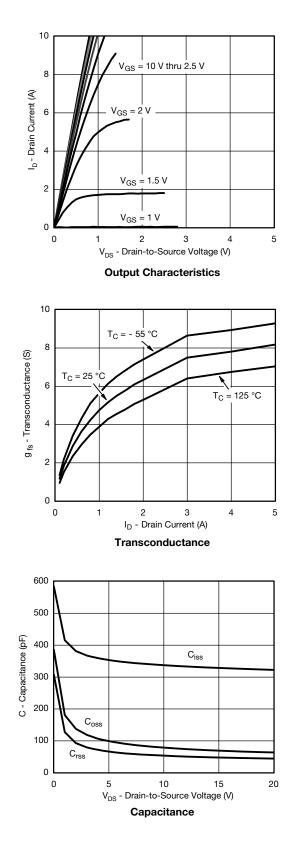
c. Independent of operating temperature.

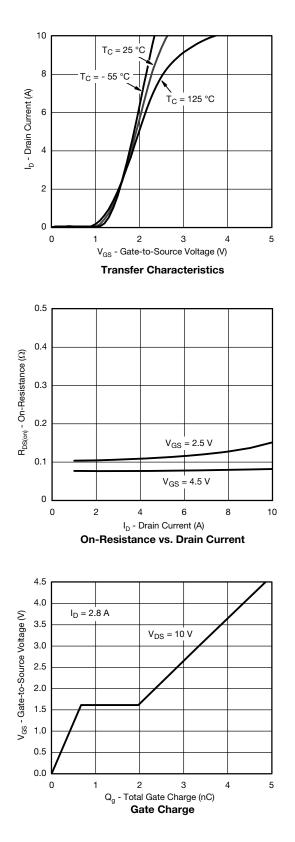
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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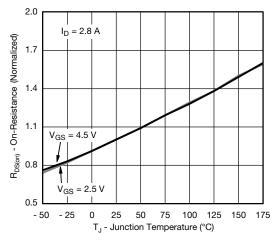
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



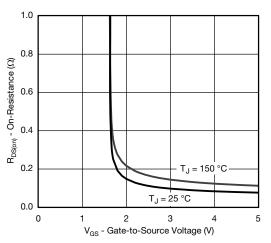




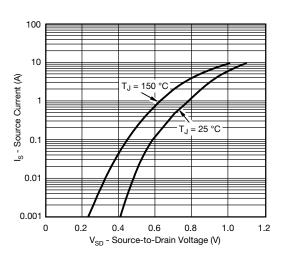
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



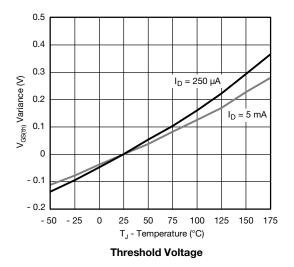
On-Resistance vs. Junction Temperature

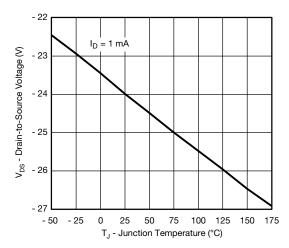


On-Resistance vs. Gate-to-Source Voltage



Source-Drain Diode Forward Voltage

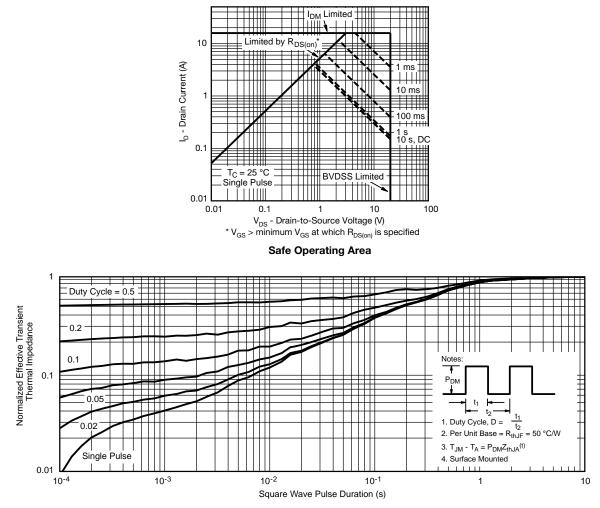




Drain Source Breakdown vs. Junction Temperature



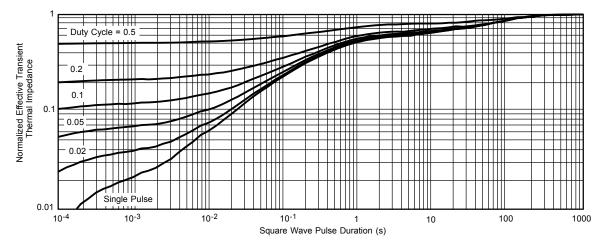
THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

Note

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

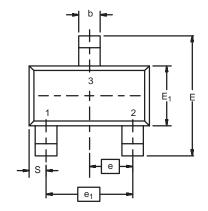
- Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

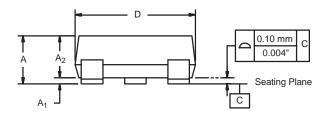
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

[•] The characteristics shown in the two graphs



SOT-23 (TO-236): 3-LEAD







Dim —	MILLIM	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
C	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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